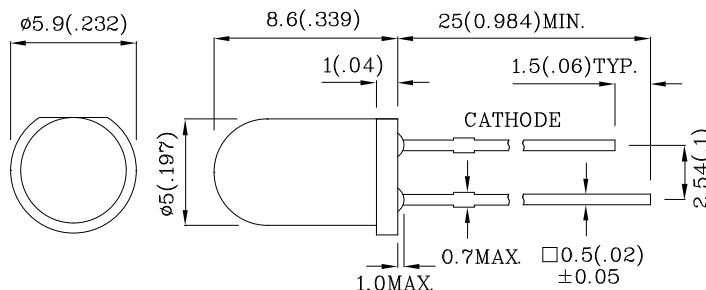


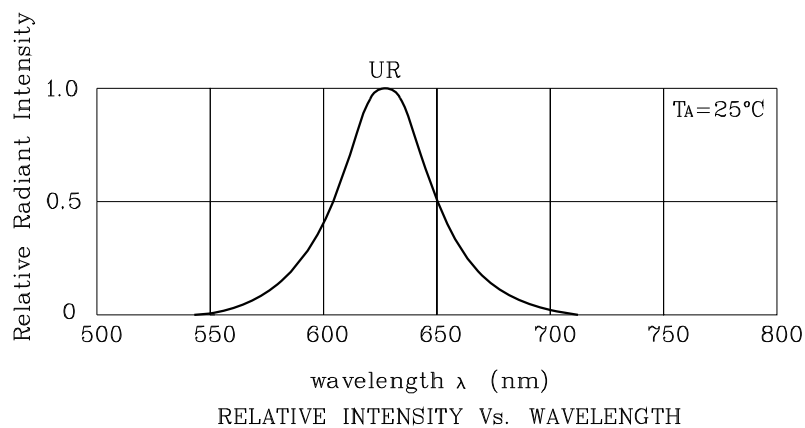


Absolute maximum ratings (TA=25°C)		UR (GaAsP/ GaP)	Unit
Reverse Voltage	VR	0.5	V
Forward Voltage	VF	14	V
Power Dissipation	PT	310	mW
Operating Temperature	TA	-40 ~ +70	°C
Storage Temperature	Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

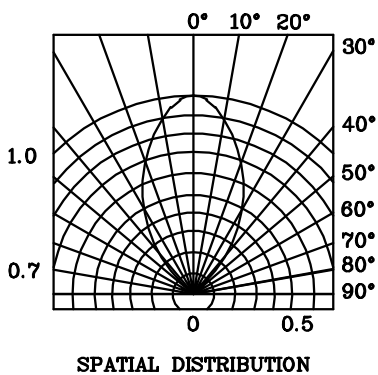
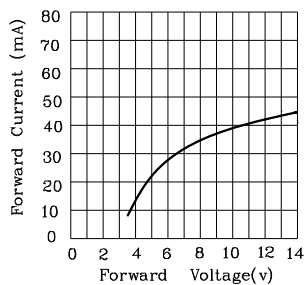
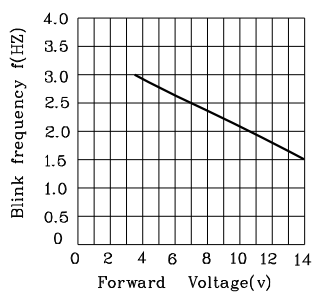


Operating Characteristics (TA=25°C)		UR (GaAsP/ GaP)	Unit
Forward Current (Min.) (VF=3.5V)	IF	8	mA
Forward Current (Typ.) (VR=5V)	IF	22	mA
Supply Current (Typ.) (VF=3.5V)	ISON	8	mA
Supply Current (Typ.) (VF=14V)	ISON	44	mA
Blink Frequency (Min.~Max.) (VF=3.5V~14V)	f	1.5~3	Hz
Wavelength of Peak Emission (Typ.)	λ P	627	nm
Wavelength of Dominant Emission (Typ.)	λ D	625	nm
Spectral Line Full Width At Half-Maximum (Typ.)	$\Delta\lambda$	45	nm

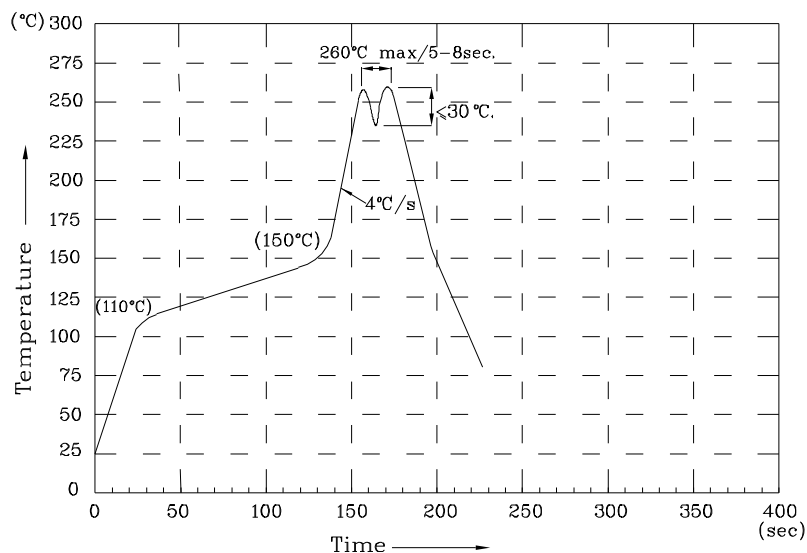
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (V= 9V) mcd	Wavelength nm λ P	Viewing Angle 2θ 1/2
				min.	typ.	
BUR53D	Red	GaAsP/GaP	Red Diffused	18	39	627
Published Date : MAR 25,2008		Drawing No : SDSA3465		V5	Checked : B.L.LIU	



❖ UR



Wave Soldering Profile For Lead-free Through-hole LED.

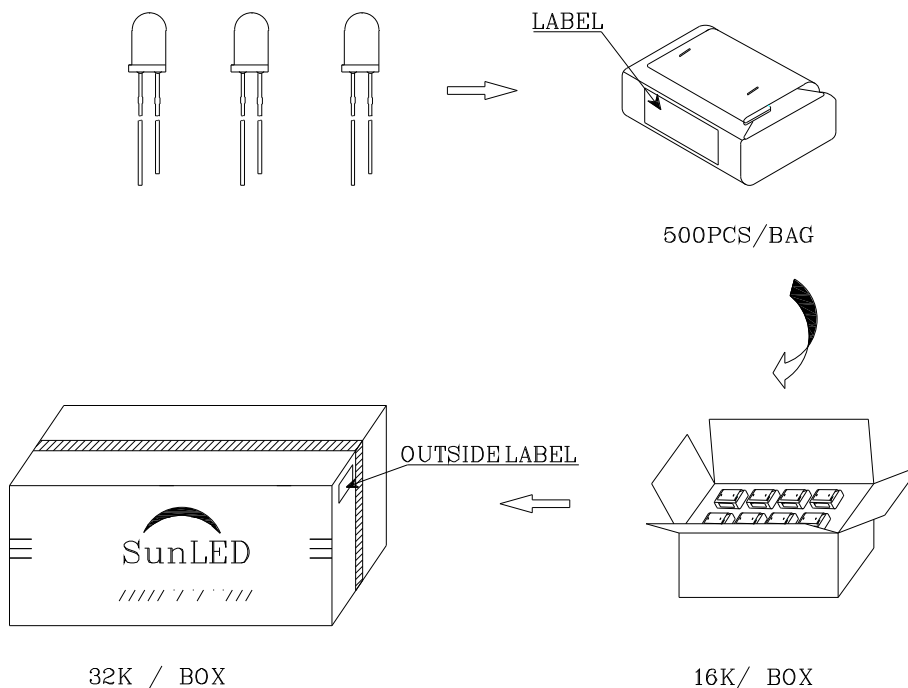


NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

PACKING & LABEL SPECIFICATIONS

BUR53D



		Q.C. Q C XX XX XXXX PASSED
P/NO : Bxx53x		
QTY : 500 pcs		CODE: XXX
S/N : XX		
LOT NO:		
 xxxxxxxxxxxxxxxxxxxx		
RoHS Compliant		